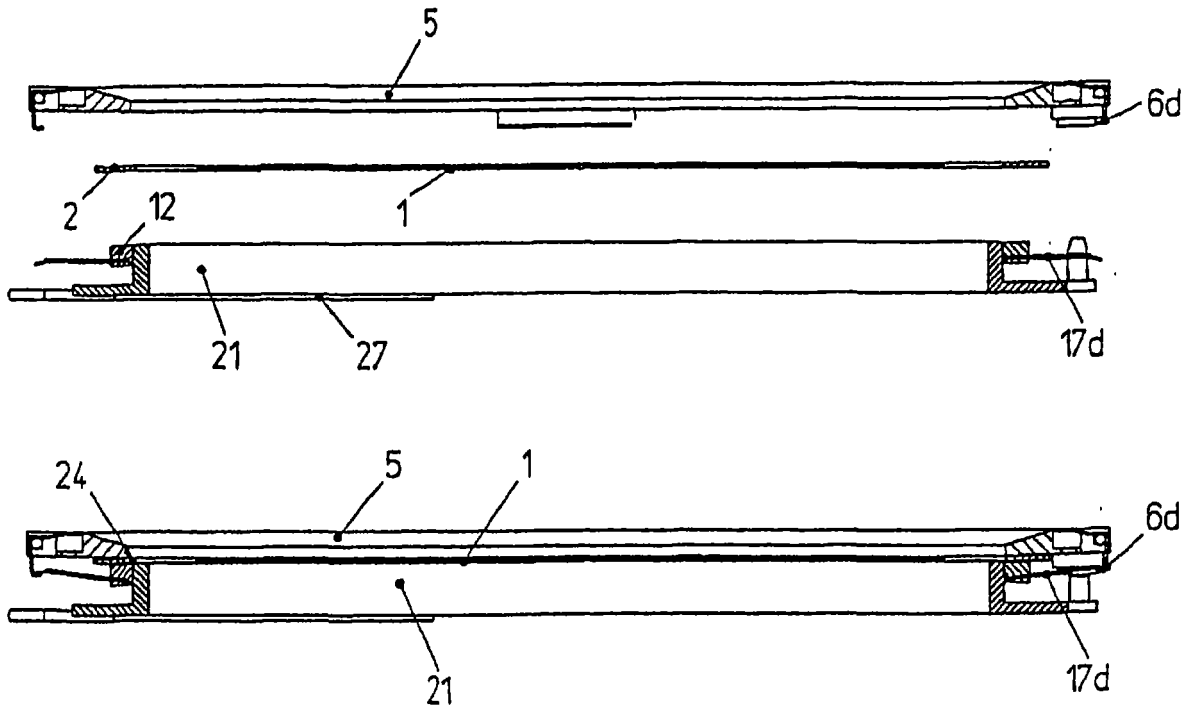
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METHOD AND DEVICE FOR PROCESSING A FLAT WORKPIECE, ESPECIALLY A SEMICONDUCTOR WAFER

ABSTRACT

The processing of semiconductor wafers is considerably simplified by the use of adapter frames. During processing the semiconductor wafer is glued in a known manner onto a carrier film which is stretched across a frame. Normally the carrier films are restretched directly on the location table of a processing machine. With the aid of an adapter frame (32) the carrier films can be put into intermediate storage already in the restretched state and manipulated in a machine. This also prevents damage to the wafer caused by sagging of the carrier film in case of large wafer diameters. Every adapter frame consists of a clamping ring (5) and a base ring (21) with a threaded ring (12) which can be screw onto same, which serves as support for the film frame (2).



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